



2006 IEEE Systems Packaging Japan Workshop

Hotel de YAMA, Hakone, Japan (Preliminary)

January 30-February 1, 2006
General Chair: Fumiyuki Kobayashi
Vice-Chair: Haruhiko Yamamoto

The IEEE Systems Packaging Japan Committee welcomes you to the 2006 IEEE Systems Packaging Japan Workshop from January 30 to February 1 in Hakone. This workshop is the eleventh one since the beginning in 1986, which covers the systems packaging technology from personal systems to high performance systems. Also a technical tour is scheduled on February 1, Wednesday afternoon. All attendees are expected to be specialists in the field and to participate in discussion. We are confident that the technical meeting will be rewarding and useful and hope your stay in the Hakone will be enjoyable.

Guidelines:

- No proceedings will be published.
- Papers present new development or critical overviews.

2006 IEEE Systems Packaging Japan Workshop Committee Members:

General Chair : Fumiyuki Kobayashi (Hitachi)
Vice-Chair : Haruhiko Yamamoto (Fujitsu Interconnect Technologies Limited)
Treasurer : Masakazu Yamamoto (Hitachi)

Members:

JAPAN

Fumiyuki Kobayashi (Hitachi)
Haruhiko Yamamoto (Fujitsu)
Masakazu Yamamoto (Hitachi)
Yutaka Tsukada (Kyocera SLC)
Seiichi Saito (Mitsubishi)
Yuzo Shimada (NEC)
Tohru Kishimoto (NTT)
Shigeyuki Ogata (Nagano OKI)
Michitaka Kimura (Renesas)
Kuniaki Takahashi (Toshiba)
Yoshitaka Fukuoka (Weisti)
Tatsuya Saito (Hitachi)
Hideo Sotokawa (Hitachi)
Hiroshi Go (Hitachi)
Koichi Koyano (Hitachi)

USA

Robert W. Guernsey (IBM)
George A. Katopis (IBM)
Robert C. Pfahl (NEMI)
Iwona Turlik (Motorola)
Leonard W. Schaper (University of Arkansas)
Aron V. Tungare, (Motorola)

Europe

Erich Klink (IBM, Germany)
Erich Beyne (Microsystems, Component&Packaging Division)
Rolf Aschenbrenner (Fraunhofer IZM)
Sean Cian O Mathuna (Tyndall National Institute)

Advisors:

Tadao Ichikawa (IT-Serve)
Toshihiko Watari (Niigata Fuji Xerox Manufacturing)
Akira Masaki (Okayama University)
Hiroshi Shibata (Osaka Institute of Technology)

2006 Session Chairs

Keynote Session :

Chair: FumiYuki Kobayashi (Hitachi)
Co-Chair: Erich Klink (IBM Germany)

Session 1: Communication Systems

Chair: Tohru Kishimoto (NTT),
Co-Chair: Seiichi Saito (Mitsubishi)
Robert C. Pfahl (IEMI),
Leonard W. Schaper (UNIV. ARKANSAS)

Session 2: Automobile, Robotics

Chair: Yoshitaka Fukuoka (WEISTI)
Co-Chair: Sean Cian O Mathuna (Tyndall National Institute)

Session 3: High Performance Computing

Chair: Haruhiko Yamamoto (Fujitsu)
Co-Chair: George A. Katopis (IBM)

Session 4: Advanced Packaging Technology

Chair: Michitaka Kimura (Renesas)
Co-chair: Robert W. Guemsey (IBM),
Rolf Aschenbrenner (Fraunhofer IZM)

Session 5: Cellular Phone and Mobile Information Systems

Chair: Yuzo Shimada (NEC),
Co-chair: Yutaka Tsukada (Kyocera SLC)
Aroon V. Tungare (Motorola)

Keynote Speakers

Not yet

2006 IEEE Systems Packaging Japan Workshop Program

January 29, Sunday		
18:00 – 19:30	Registration	
January 30, Monday		
9:00 - 10:00	Registration	
10:00 – 11:40	Keynote Session: Chair: Fumiyuki Kobayashi (Hitachi) Co-Chair: Erich Klink (IBM Germany)	
11:40 – 12:00	Take-gathering-photos in a garden	
12:00 – 13:00	Lunch	
13:00 – 15:30	Session 1: Communication Systems Chair: Tohru Kishimoto (NTT), Co-Chair: Seiichi Saito (Mitsubishi) Robert C. Pfahl (IEMI), Leonard W. Schaper (UNIV. ARKANSAS)	
15:30 – 16:00	Coffee Break	
16:00 – 18:30	Session 2: Automobile, Robotics Chair: Yoshitaka Fukuoka (WEISTI) Co-Chair: Sean Cian O Mathuna (Tyndall National Institute)	
19:00 – 21:30	Banquet	
January 31, Tuesday		
8:00 – 10:30	Session 3: High Performance Computing Chair: Haruhiko Yamamoto (Fujitsu) Co-Chair: George A. Katopis (IBM)	
10:30 – 10:40	Coffee Break	
10:40 – 12:10	Session 4: Advanced Packaging Technology Chair: Michitaka Kimura (Renesas) Co-Chair: Robert W. Guernsey (IBM) Rolf Aschenbrenner (Fraunhofer IZM)	
12:10 – 12:50	Lunch	
12:50 – 13:50	Session 4: Advanced Packaging Technology (continued)	
13:50 – 17:40	Short Sight Seeing Tour (Optional)	
13:50 – 14:15	To Hakone-en on hotel's bus or by walk	(free)
14:15 – 15:00	To Hakone-Sekisho-Ato on a ship	(970JPY)
15:00 – 15:30	To Hakone-sekisho-shiryu-kan by walk	(free, close at 5pm)
15:30 – 17:00	To Hakone-Narukawa Museum by walk	(1200JPY, close at 5pm)
17:10 – 17:40	To hotel on hotel's bus or by walk	(free)
18:30 – 21:00	Dinner Party	

February 1, Wednesday	
8:00 – 10:30	Session 5: Cellular Phone and Mobile Information Systems Chair: Yu zo Shimada (NEC) Co-Chair: Yutaka Tsukada (Kyocera SLC) Aroon V. Tungare (Motorola)
10:30 – 11:00	Closing
11:00 – 18:00	Technical Tour: Lunch in buses Technical tour Stopping at Kokubunji station of JR Chuo line, tour will end at Shinjuku station of JR Chuo line on buses.